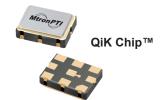


Product Features

- Multiple Output Frequencies (2, 3, or 4) Selectable
- QiK Chip™ Technology
- Superior Jitter Performance (less than 0.25 ps RMS, 12 kHz 20 MHz)
- SAW replacement better performance
- Frequencies from 50 MHz 1.4 GHz (LVDS/LVPECL/CML)
- Frequencies from 10 MHz 150 MHz (HCMOS)





Product Description

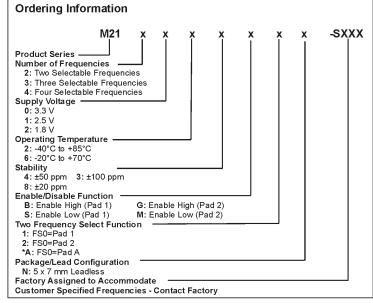
The multiple frequency oscillator utilizes MtronPTI's Qik Chip[™] technology to provide a very low jitter clock for all output frequencies. The M21x is available with up to 4 different frequency outputs from 10MHz through 1.4 GHz. The M21x utilizes the stable fundamental 3rd overtone crystal and the Qik Chip[™] IC to provide the wide range of output frequencies. Using this design approach, the M21x provides exceptional performance in frequency stability, jitter, phase noise and long term reliability.

Product Applications

- Global/Regional selection
- Forward Error Correction (FEC) / Selectable Functionality applications
- Telecommunications such as SONET / SDH / DWDM / FEC / SERDES / OC-3 thru OC-192
- 1-2-4-10 Gigabit Fibre Channel
- · Wireless base stations / WLAN / Gigabit Ethernet

- xDSL, Network Communications
- Avionic flight controls
- Military communications
- Clock and data recovery
- Low jitter clock generation
- Frequency margining

Product Ordering Information



Frequency Select Truth Table							
FS1 FS0							
Frequency 1	High	High					
Frequency 2	High	Low					
Frequency 3	Low	High					
Frequency 4	Low	Low					

NOTE: Logic Low = 20% Vcc max. Logic High = 80% Vcc min.

^{*}For three and four frequency selections, FS0=Pad A



Performance Characteristics

PARAMETER Symbol Min. Typ. Max. Units Condition/Note Frequency Range F 50 1400 MHz LVPECL/LVDS/HCMOS Operating Temperature TA -20 to +70 °C Customer Spec Storage Temperature Ts -55 +125 °C Frequency Stability ΔF/F See Ordering Information ppm See Note 2	/CML - See Note 1					
Operating Temperature TA -20 to +70	ified					
-40 to +85	ified					
-40 to +85 °C Storage Temperature Ts -55 +125 °C	eu					
Frequency Stability Δ F/F See Ordering Information ppm See Note 2						
Aging						
1st Year -3 +3 ppm						
Thereafter (per year) -1 +1 ppm						
Supply Voltage Vcc 1.71 1.8 1.89 V						
2.375 2.625 V						
3.135 3.3 3.465 V	20/01/1					
Input Current Icc 125 mA LVPECL/HCMC)S/CML					
Load 105 mA LVDS See Note 3						
	c					
50 Ohms to (Vcc -2) Vdc LVPECL Wavef 100 Ohm differential load LVDS/CML Wav						
15 pF CMOS Wavefor						
15 pr CMOS Wavelor						
Symmetry (Duty Cycle) 45 55 % LDPECL: Vdd -	1.5 V					
Output Skew 20 ps LVPECL						
15 ps CML						
20 ps LVDS						
ਨ Differential Voltage 500 700 900 mVppd LVDS						
[을 0.7 0.95 1.20 Vpp CML						
Symmetry (Duty Cycle) 45 55 % LDPECL: Vdd - LVDS: 1.25 V						
Uutput Voltage						
90% Vdd						
Logic "0" Level						
10% Vdd HCMOS						
Rise/Fall Time Tr/Tf 0.23 0.35 ns @ 20/80% LVP	ECL					
6.0 ns Ref. 10%-90%						
Enable Euroption 900/ Vice min. or N/C: Output pative						
Option B 0.5V max: Output disables to high-Z Customer Spec	illed					
Enable Function 0.5V max or N/C: Output active Customer Spec	ified					
Option S 80% Vcc min. Output disables to high-Z	ilicu					
Tristate Function Input Logic "1" or floating: output active Customer Spec	ified					
Input Logic "U": output disables to high-Z						
Frequency Selection See Truth Table						
	om of frequency					
Start up Time 10 ms						
Phase Jitter	/CMI					
@ 622.08 MHz						
@ 125 MHz 0.50 ps RMS HCMOS (12 kH						
© 1-2						
T 1	Per MIL-STD-202, Method 213, Condition C (100 d's 6 mS duration 1/2 sinewaye)					
Mechanical Shock Per MIL-STD-202, Method 213, Condition C (100 g's, 6 mS duration, ½ sinewaye						
Mechanical Shock Per MIL-STD-202, Method 213, Condition C (100 g's, 6 mS duration, ½ sinewave Wibration Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)	-)					
Mechanical Shock Per MIL-STD-202, Method 213, Condition C (100 g's, 6 mS duration, ½ sinewave Vibration Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz) Per MIL-STD-202, Method 112, (1x10* atm. cc/s of Helium)						
Mechanical Shock						
Vibration						

Note 1: Contact factory for standard frequency availability over 945 MHz.

Note 2: Stability is inclusive of initial tolerance, deviation over temperature, shock, vibration, supply voltage, and aging for one

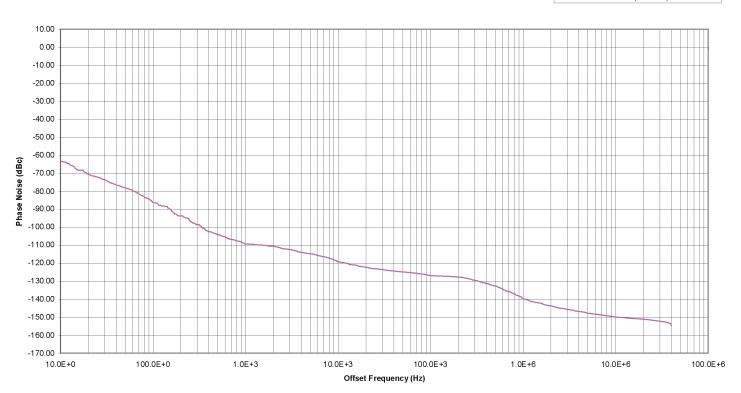
year at 50°C mean ambient temperature.

Note 3: See Load Circuit Diagram in this datasheet. Consult factory with nonstandard output load requirements.

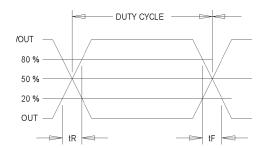


Phase Noise Plot

— Phase Noise (dBc/Hz) 622.08MHz



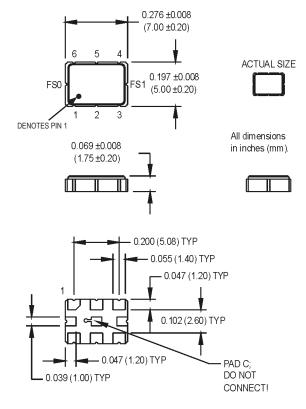
Output Waveform



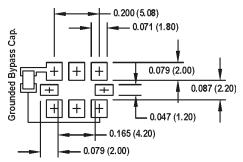
Output Waveform: LVDS/CML/LVPECL



Product Dimension & Pinout Information



SUGGESTED SOLDER PAD LAYOUT



PAD 1 ENABLE

Pad1: Enable/Disable or Tristate

Pad2: N/C or FS0

Pad3: Ground

Pad4: Output Q (LVPECL, LVDS, CML, HCMOS)

Pad5: Output Q (LVPECL, LVDS, CML) N/C for HCMOS

Pad6: Vcc

PadA: FS0 or N/C

PadB: FS1

PadC: Do not connect!

PAD 2 ENABLE

Pad1: N/C or FS0

Pad2: Enable/Disable or Tristate

Pad3: Ground

Pad4: Output Q (LVPECL,LVDS,CML,HCMOS)

Pad5: Output Q (LVPECL, LVDS, CML) N/C for HCMOS

Pad6: Vcc

PadA: FS0 or N/C

PadB: FS1

PadC: Do not connect!



Handling Information

Although protection circuitry has been designed into the M21x oscillator, proper precautions should be taken to avoid exposure to electrostatic discharge (ESD) during handling and mounting. MtronPTI utilizes a human-body model (HBM) and a charged-device model (CDM) for ESD-susceptibility testing and protection design evaluation. ESD voltage thresholds are dependent on the circuit parameters used to define the mode. Although no industry-wide standard has been adopted for the CDM, a standard HBM (resistance = 1500 Ω , capacitance = 100 pF) is widely used and therefore can be used for comparison purposes. The HBM ESD threshold presented here was obtained using these circuit parameters.

Model	ESD Threshold, Minimum	Unit
Human Body	1500*	V
Charged Device	1500*	V

^{*} MIL-STD-833D, Method 3015, Class 1

ATTENTION Static Sensitive Devices Handle only at Static Safe Work Stations

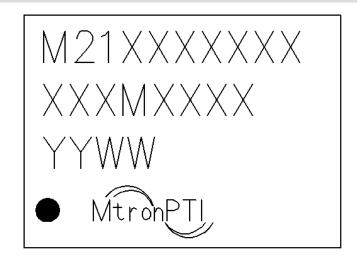
Quality Parameters

Environmental Specifications/Qualification Testing Performed on the M21x Clock Oscillator							
Test	Test Method	Test Condition					
Electrical Characteristics	Internal Specification	Per Specification					
Frequency vs. Temperature	Internal Specification	Per Specification					
Mechanical Shock	MIL-STD-202, Method 213, C	100 g's					
Vibration	MIL-STD-202, Method 201-204	10 g's from 10-2000 Hz					
Thermal Cycle	MIL-STD-883, Method 1010, B	-55 Deg. C to +125 Deg. C, 15 minute Dwell, 10 cycles					
Aging	Internal Specification	168 Hours at 105 Degrees C					
Gross Leak	MIL-STD-202, Method 112	30 Second Immersion					
Fine Leak	MIL-STD-202, Method 112	Must meet 1x10 ⁻⁸					
Solderability	MIL-STD-883, Method 2003	8 Hour Steam Age – Must Exhibit 95% coverage					
Resistance to Solvents	MIL-STD-883, Method 2015	Three 1 minute soaks					
Terminal Pull	MIL-STD-883, Method 2004, A	2 Pounds					
Lead Bend	MIL-STD-883, Method 2004, B1	1 Bending Cycle					
Physical Dimensions	MIL-STD-883, Method 2016	Per Specification					
Internal Visual	Internal Specification	Per Internal Specification					

Part Marking Guide

Line 1: Model Number Line 2: Frequency Line 3: Date Code

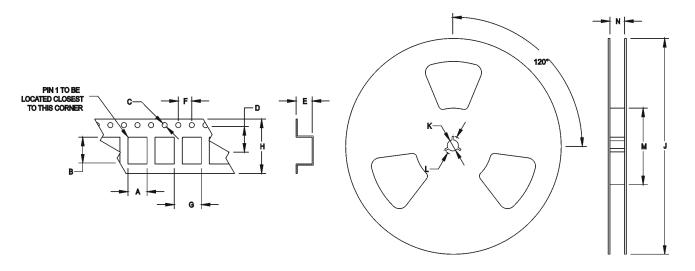
Line 4: Pin 1 Indicator / MtronPTI





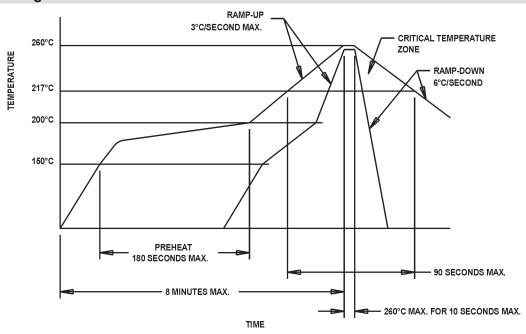
Tape & Reel Specifications

(all measurements are in mm)	Α	В	С	D	E	F	G	Н	1	J	K	L
M21x	6.51	9.29	1.5	7.5	2.8	4	8/12	16	180-330	13	21	60-100



Standard Tape and Reel: 1000 parts per reel

Maximum Soldering Conditions

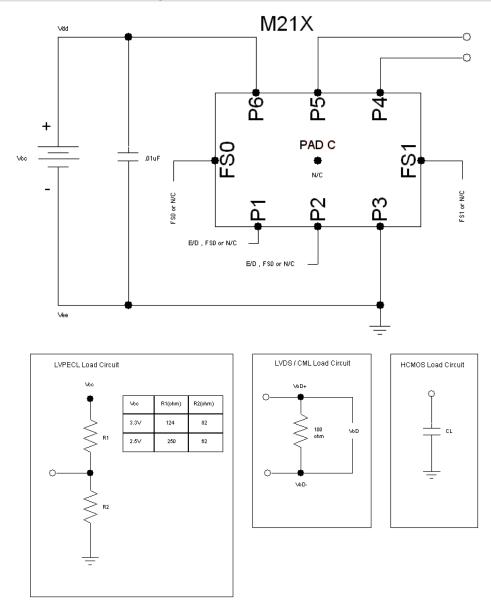


Solder Conditions

Note: Exceeding these limits may damage the device.



Typical Test Circuit & Load Circuit Diagrams



Product Revision Table

Date	Revision	PCN Number	Details of Revision
7/20/07	А	10118	IC Revision to improve phase noise and electrical performance

For custom products or additional specifications contact our sales team at 800.762.8800 (toll free) or 605.665.9321

For more information on this product visit the MtronPTI website at www.mtronpti.com